



NAMIFAB UGENT

dr. ir. Thomas Vervust



<u>OVERVIEW</u>

- Introducing NaMiFab UGent
- \rightarrow Use case examples
- → NaMiFab expertise
- \rightarrow Collaboration with NaMiFab
- → Contact information



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NaMiFab UGent:

- \rightarrow Is an expertise center for Nano-and Microfabrication.
- \rightarrow We structure and combine different materials at nano- and microscale.
- \rightarrow We design and fabricate various components and systems.

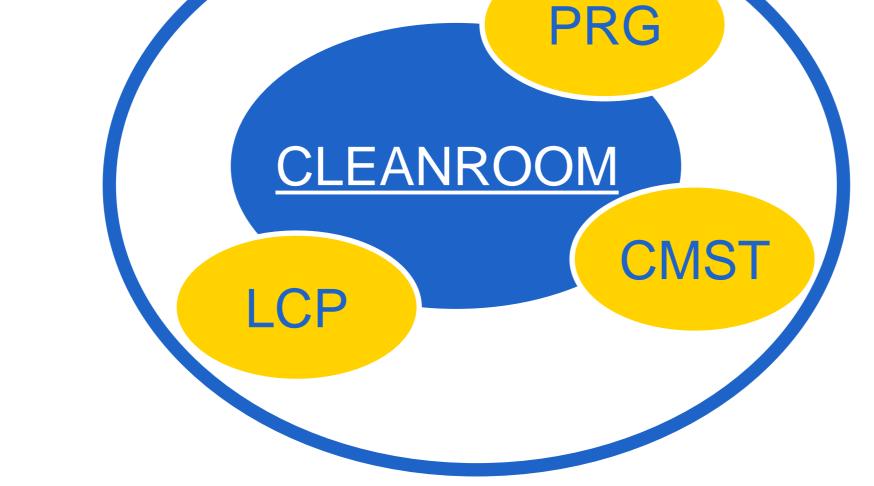






Cleanroom Tech Lane Ghent Science Park - Campus A

Technologiepark-Zwijnaarde 914 – 926 9052 Ghent



Expertise Centre for Nano- and Microfabrication



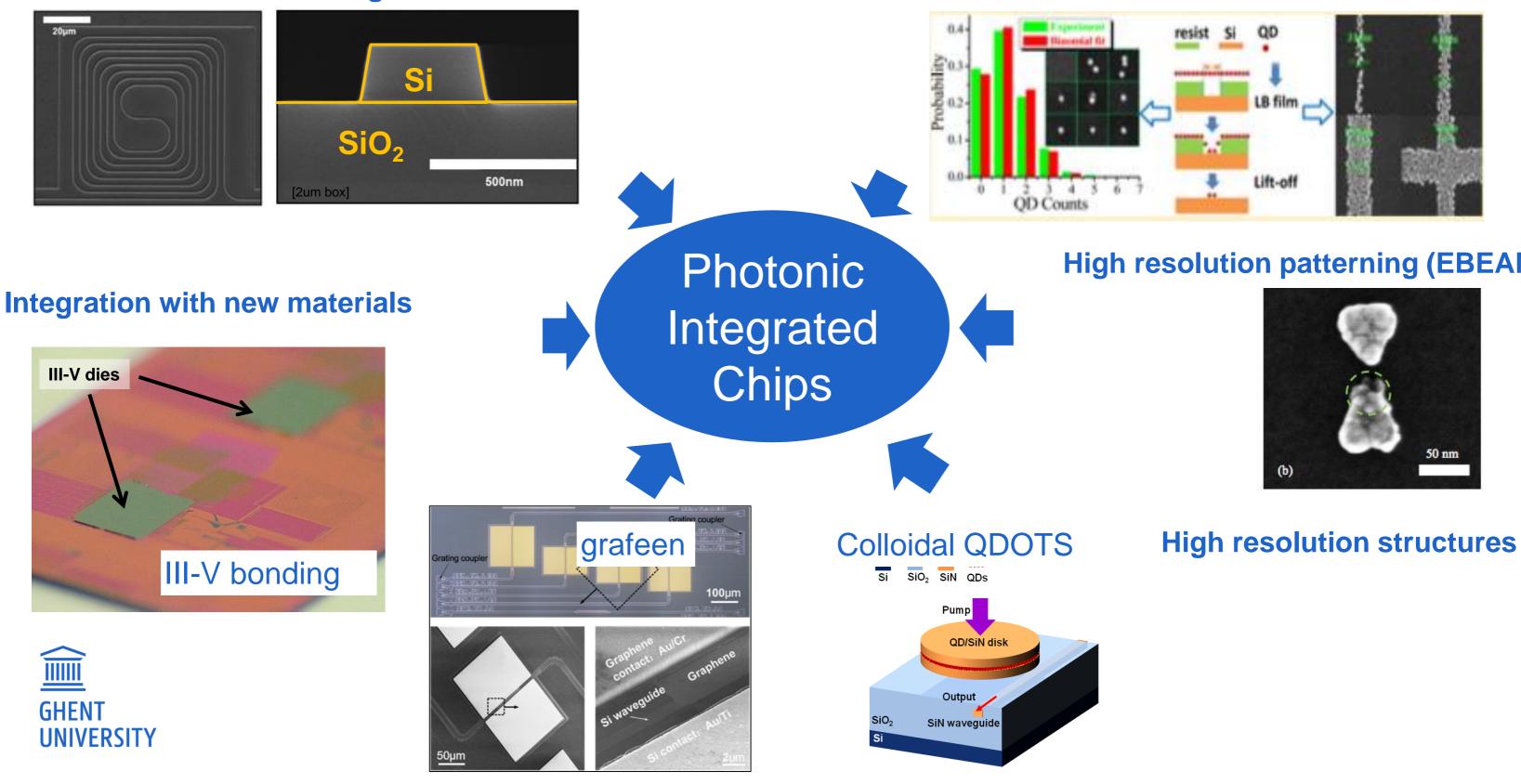
PRG: Photonics Research Group CMST: Centre for Microsystems Technology LCP: Liquid Crystals and Photonics Group

NaMiFab UGent

PRG - TECHNOLOGY PLATFORMS

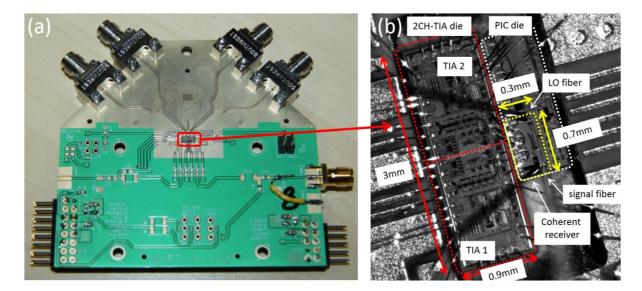
Silicon & SiN Waveguides

High resolution imaging (SEM, FIB)

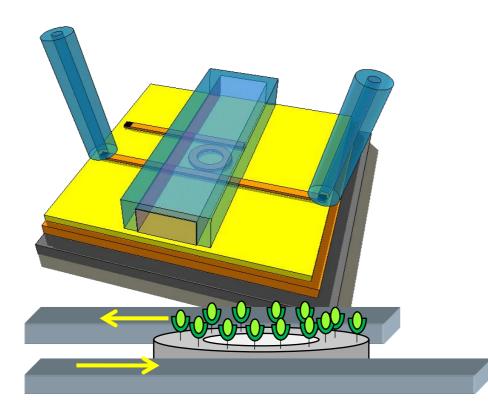


High resolution patterning (EBEAM)

PRG - APPLICATION EXAMPLES

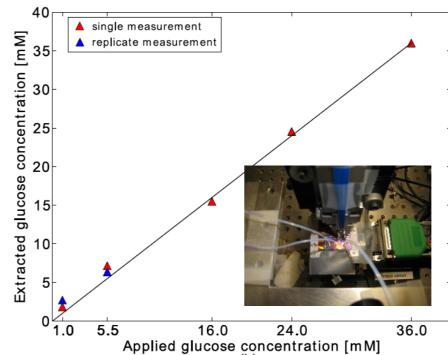


High-speed opto-electronic transceivers





Biosensing (e.g. detection of Tuberculosis)



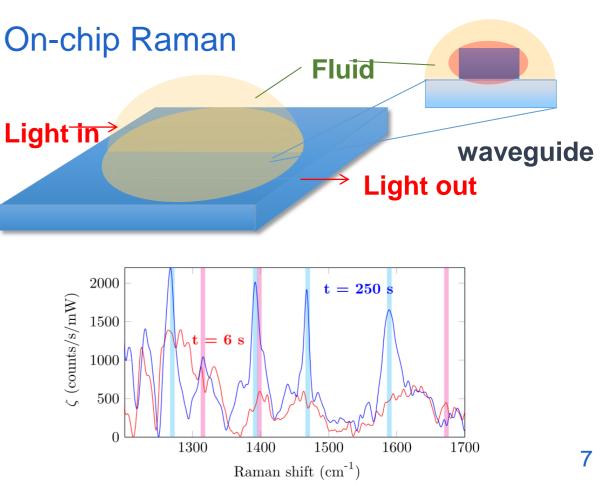
Light in



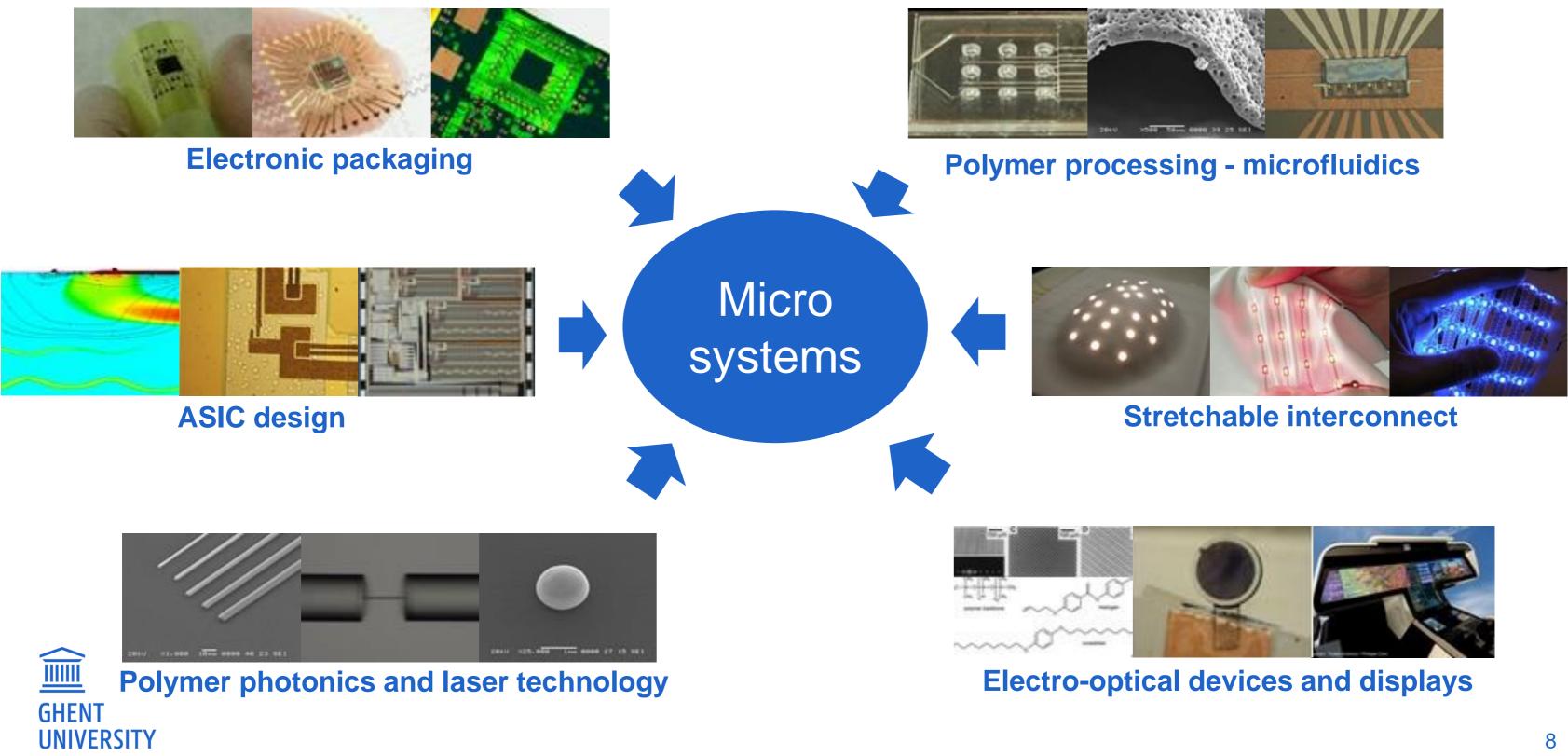
On-chip spectroscopy

- **Glucose detection** -
- Gas-sensing _

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CMST - TECHNOLOGY PLATFORMS

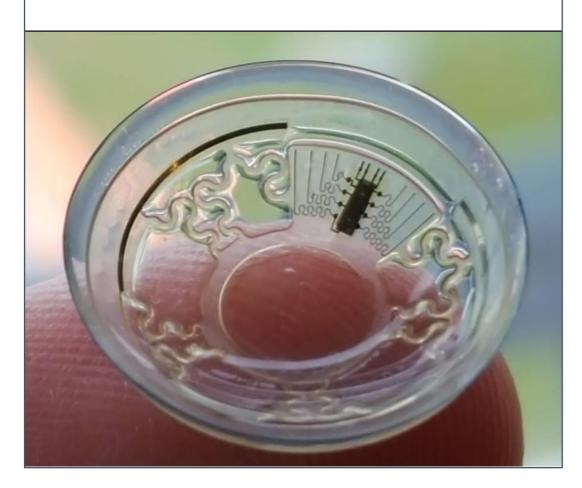




CMST - APPLICATION EXAMPLES

Smart contact lens

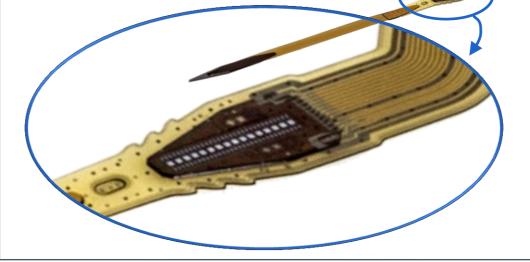
- Electronic platform with sensors, controller, communication, electro-optic switching, battery...
- Applications: artificial iris, presbyopia correction, sensing...



Implantable PNS probe

- Implantable peripheral recording and stimulation system for closedloop sensory control of prostheses
- Technology for electronic component integration, miniaturization, biocompatibility.

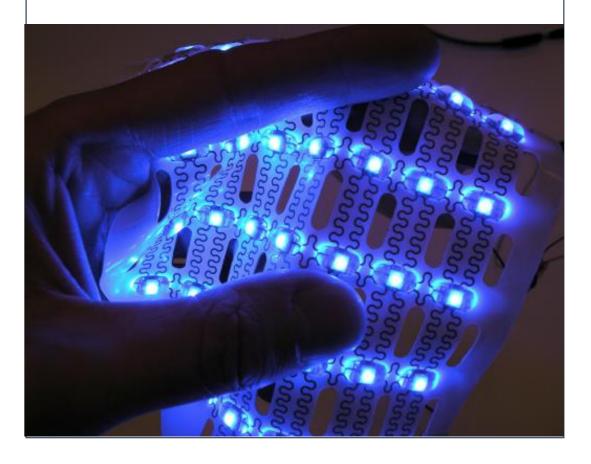
This work was sponsored by the Defense Advanced Research Projects Agency (DARPA) BTO under the auspices of Dr. Doug Weber through the Space and Naval Warfare Systems Center. Pacific Grant/Contract No. N66001-15-C-4018 to the University of Florida. This presentation is approved for Public Release by DARPA, Distribution Unlimited.





Stretchable light source

- Technology for stretchable • interconnections in polymer and component mounting
- Applications: luminaires, RSI • pain relief bandage...



LCP - TECHNOLOGY PLATFORMS

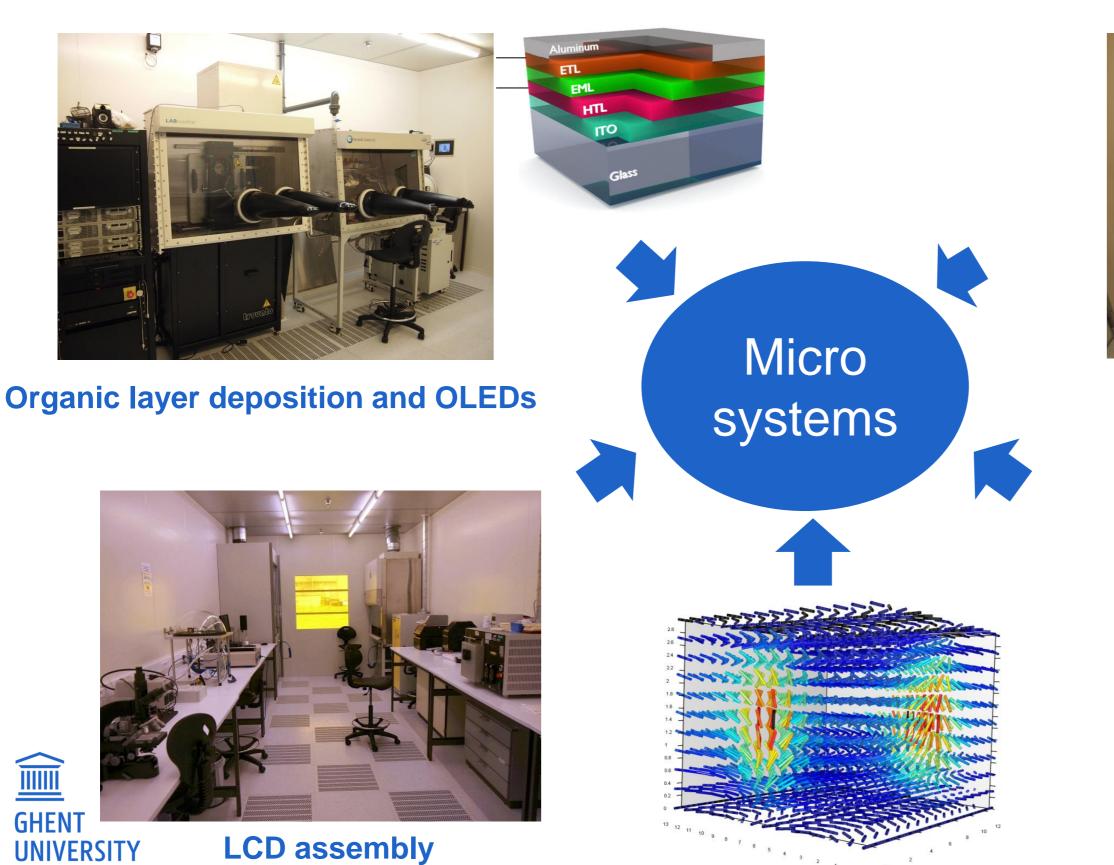
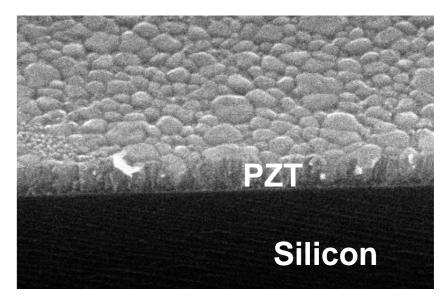


Photo-alignment of LCDs



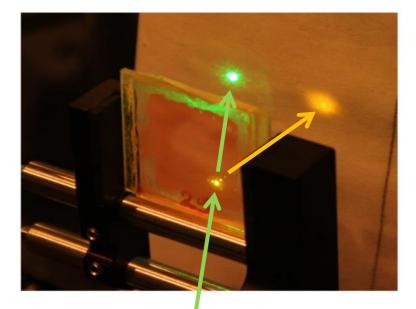
Atomic layer deposition



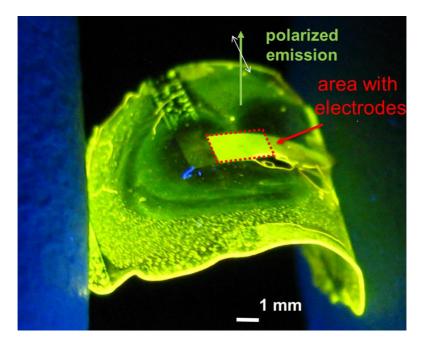
Sol Gel of PZT

LCP - APPLICATION EXAMPLES

Tunable ring resonators with LC

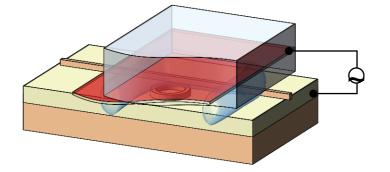


Tunable liquid crystal lasers

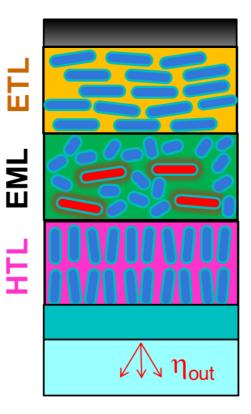


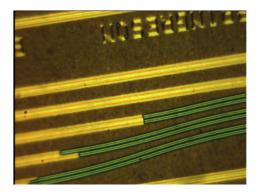


Polarized light emitter

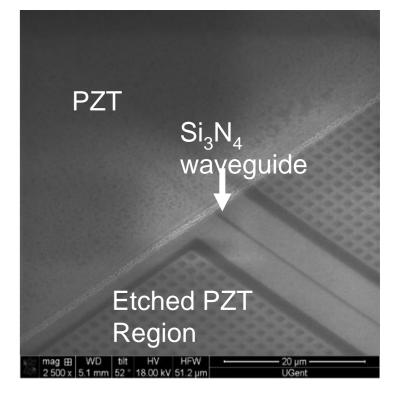


Anisotropic OLED devices

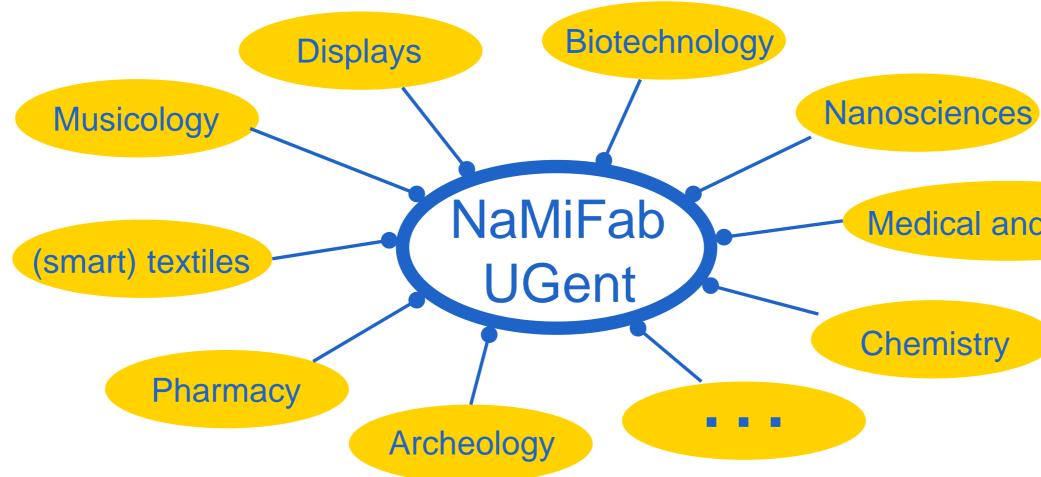








High speed PZT modulators



Our mission

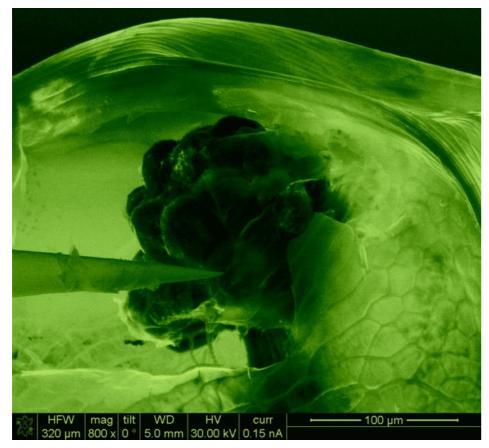
Open up state of the art test and research infrastructure for the entire UGent research community, working in diverse domains.



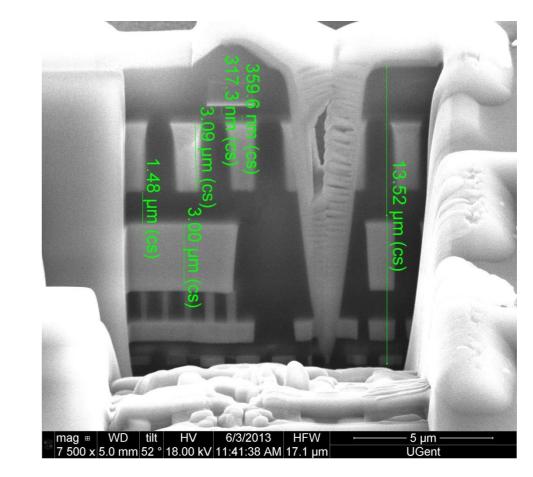
Medical and health

High-Resolution Imaging using Electron Microscopy and Focussed Ion Beam Cross-Sections

- \rightarrow Nanometer resolution imaging with Electron Microscope
- \rightarrow Focussed Ion Beam allows to make local cuts to see "into" material



Nanoprobe needle inserted in eye of Daphnia (water flea)



mistakes in electronic ICs

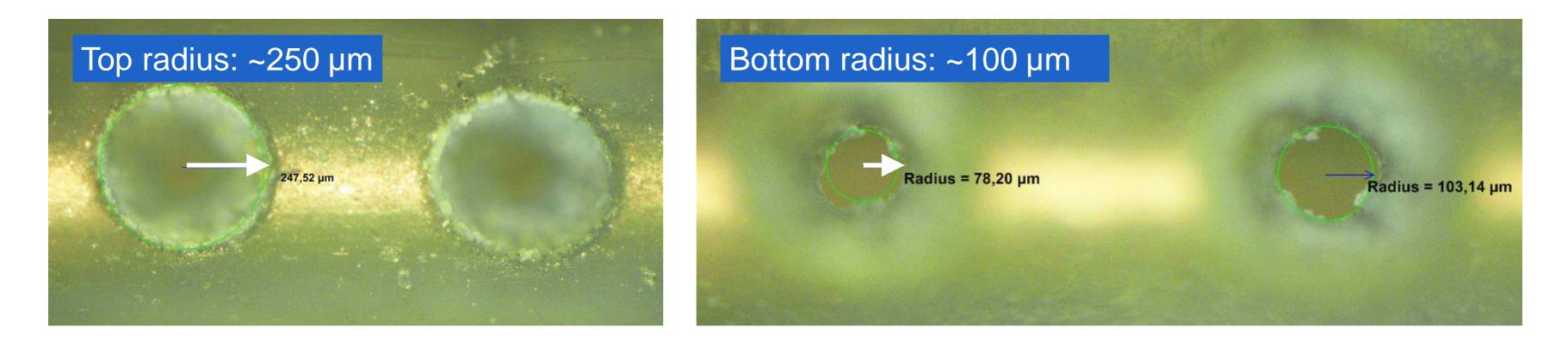


Reverse engineering and correcting

Laser ablation of PDMS catheter for controlled drug release

 \rightarrow Request from Biofluid, Tissue and Solid Mechanics for Medical Applications group (Prof. Patrick Segers)

• Perforations in a PDMS catheter (tube inner diameter of ~1mm, 0.4mm thickness)



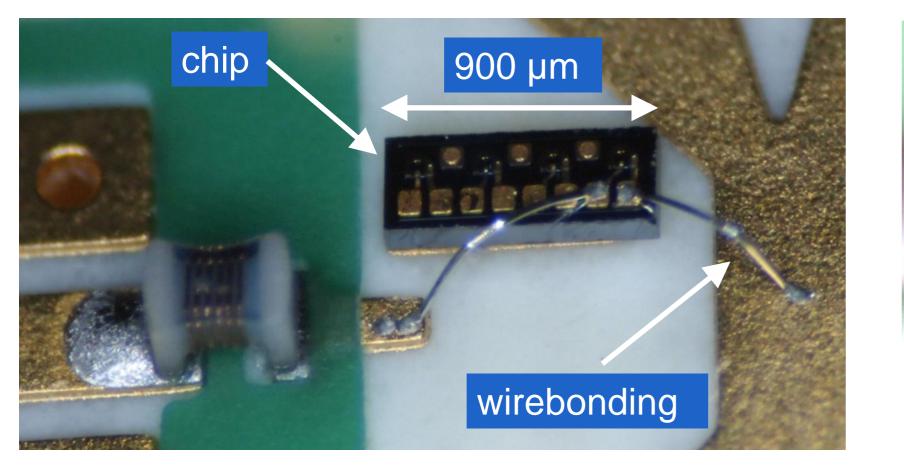


Laser ablation was done with pico- and femtosecond laser setup

Wirebonding and pigtailing of a photodiode chip

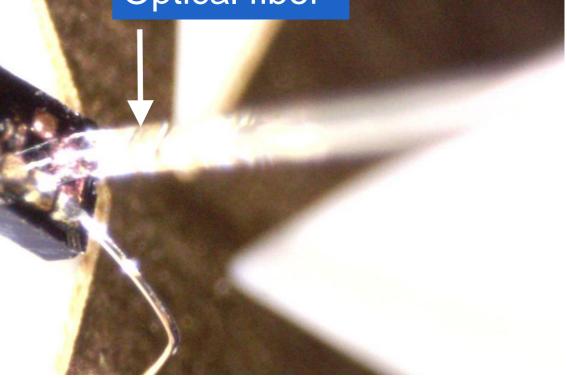
→ Request from Electromagnetics research group (Prof. Hendrik Rogier)

- Assembly off a photodiode chip onto a PCB
- Optical connection between chip and an optical fiber





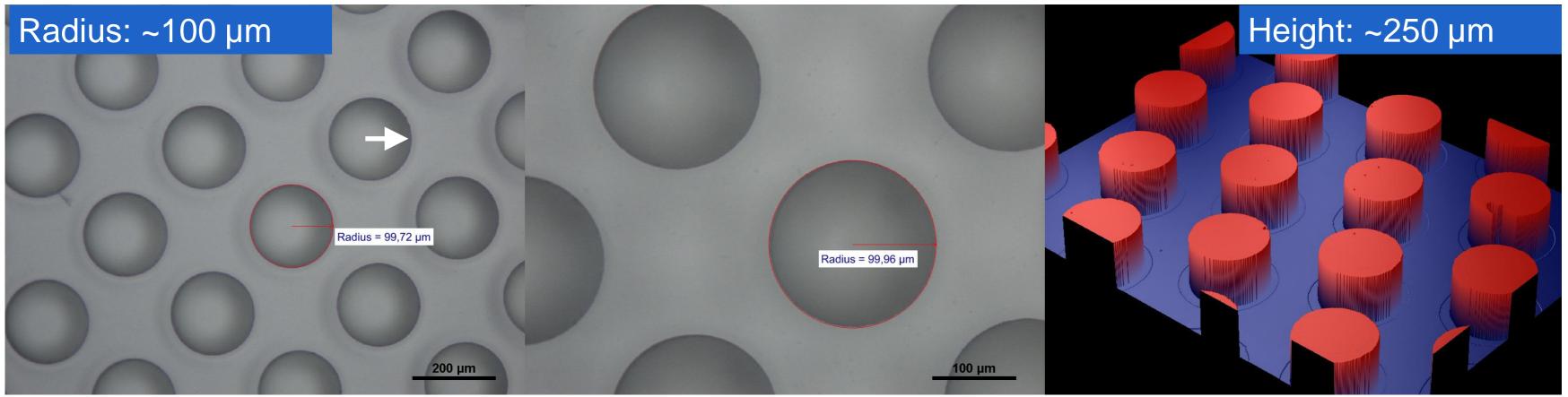
Optical fiber



Fabrication of a microwell-based tissue culture platfrom

→ Request from Tissue Engineering and Biomaterials research group (Prof. Ria Cornelissen)

- Fabrication of a PDMS mold to produce a microwell-based tissue culture platform
- The PDMS molds should contain micro-sized cylindrical sticks



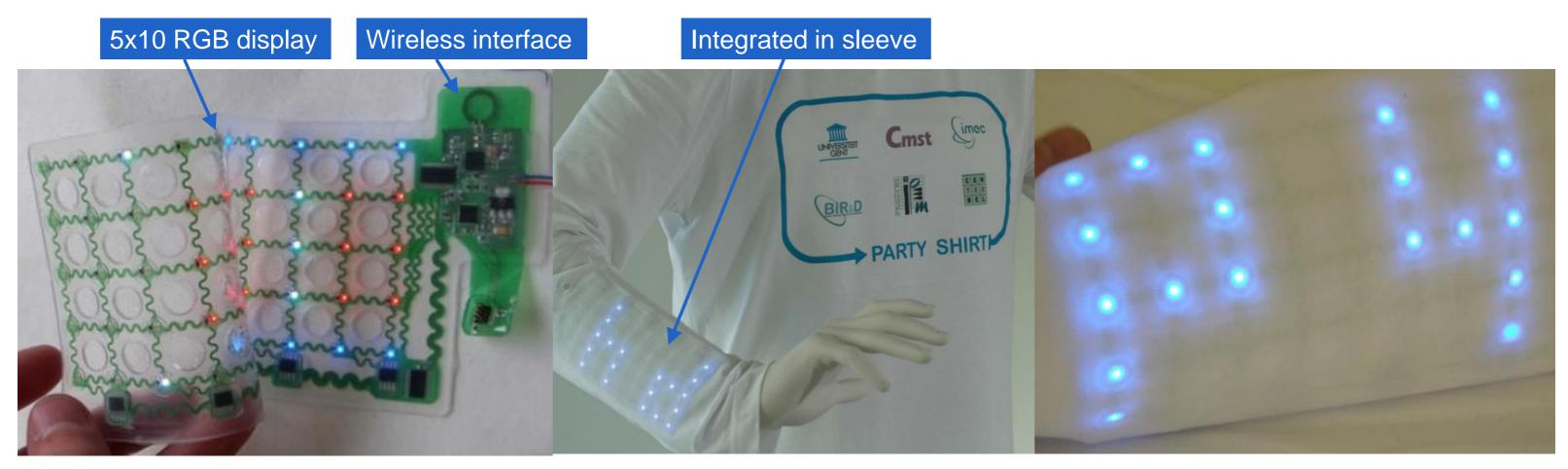


Paper: High Throughput Micro-Well Generation of Hepatocyte Micro-Aggregates for Tissue Engineering, Gevaert, E. et al., Plos One (2014) 16

Ria Cornelissen) le culture platform

Fabrication of a stretchable and textile integrated LED display

 \rightarrow This was developed in the frame of a BIR&D award winning multidisciplinary master thesis \rightarrow The resulting "party shirt" was used by the IPEM institute for systematic musicology (Prof. Marc Leman)

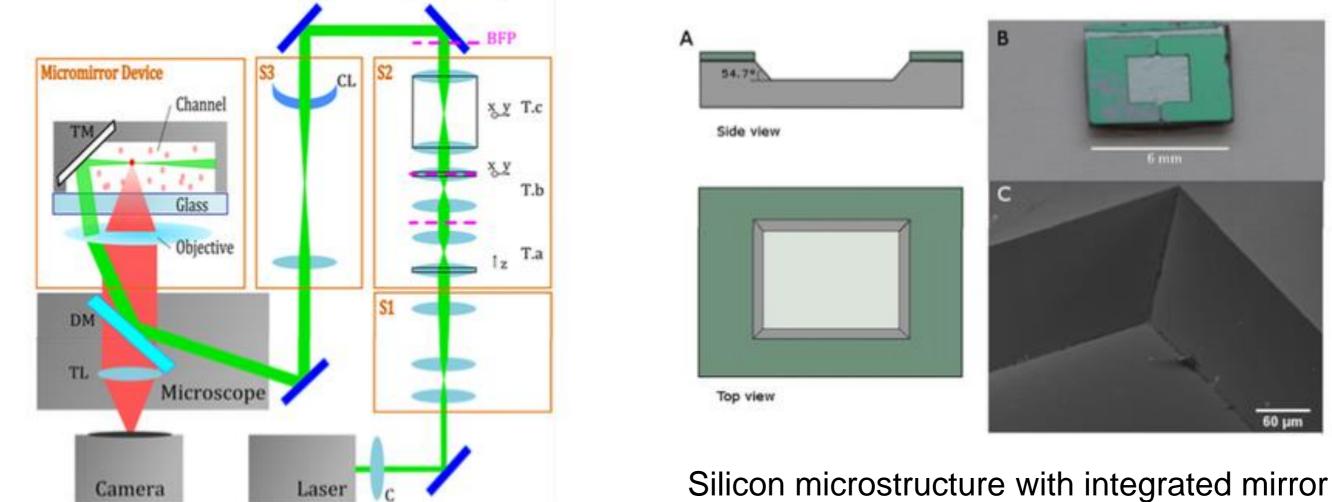




Published: Synchronizing music and movement with BeatLED: an interactive musical social game, T. De Nies et al., Journal of new music research (2012)

Silicon microstructure for Light Sheet Microscopy

- \rightarrow Request from Laboratory of General Biochemistry and Physical Pharmacy (Prof. Kevin Braekmans)
- \rightarrow Light Sheet Microscopy gains increasing interest but requires complex optical setup
- → Relatively simple silicon microstructure overcomes this problem





Published: Microfabricated devices for single objective single plane illumination microscopy (SoSPIM), Zagato e.a., Optics Express, 2017)

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- \rightarrow Execution of <u>small exploratory projects</u>, which can form the base for more extended collaborative project proposals => create new ideas and opportunities for original interdisciplinary research subjects
- \rightarrow Knowhow and infrastructure for designing, realizing and inspecting <u>nano- and microsystems</u> of very diverse shape, dimensions and complexity

(List of test and research infrastructure on <u>www.ugent.be/namifab/en/infrastructure</u>)



Nano- and microfabrication technologies:

Photolitography (pattern definition)

- \rightarrow Photomask alignment and exposure (resolution down to 800nm)
- \rightarrow Laser direct imaging (resolution down to 1µm)
- \rightarrow Electron beam lithography (resolution down to 10nm)

Layer deposition

- \rightarrow Spin coating
- \rightarrow Plasma deposition
- \rightarrow Sputter deposition
- \rightarrow Electron beam evaporation
- \rightarrow Thermal evaporation for deposition of organic layers
- \rightarrow Atomic layer deposition (aluminium oxide)

Etching

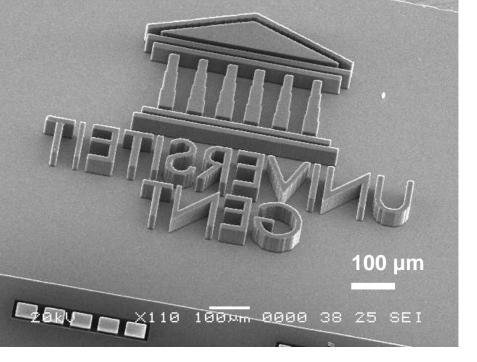
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- \rightarrow Development, etch and strip line for flexible PCBs
- \rightarrow Plasma etching (RIE, ICP, Oxygen)
- \rightarrow HF-vapor etching









Plasma deposition



Thermal evaporation

Flexible PCB processing



Plasma etching ²⁰

Nano- and microfabrication technologies:

Material structuring

- \rightarrow Laser structuring, cutting, drilling and welding on a variety of substrates
- \rightarrow Microinjection moulding of small parts (<1g)
- \rightarrow Dicing, lapping, polishing
- \rightarrow Lamination, imprinting
- \rightarrow Vacuum forming

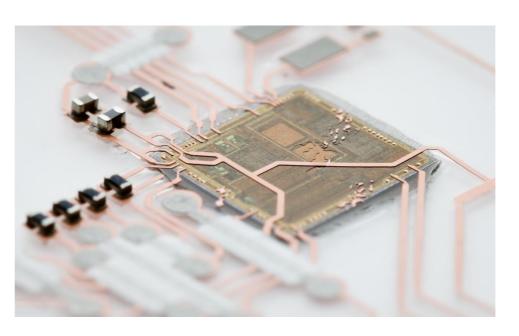
Assembly

- \rightarrow Die and flip-chip bonding (± 5µm accuracy)
- \rightarrow Accurate (± 1µm) placement of chips and toher 3D structures
- \rightarrow Micro-Transfer-printing (µTP)
- \rightarrow Wafer bonding
- \rightarrow Automated needle dispensing
- \rightarrow Screenprinting
- \rightarrow Reflow soldering
- \rightarrow Wire bonding
- \rightarrow Aerosol-jet printing (print metallic conductive inks)

→ Liquid crystal device assembly GHENT UNIVERSITY



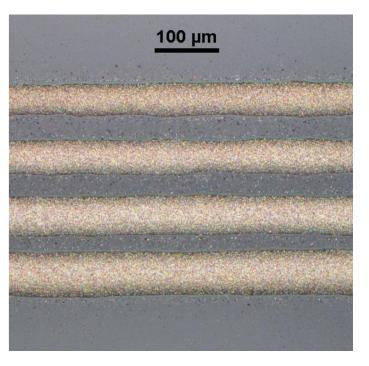
Micromoulding



Assembled smart label



Vacuum forming



Sample inspection:

Microscopy

- \rightarrow Optical microscopy (mm to μm size features)
- \rightarrow Electron microscopy: SEM, FEG-SEM with in situ FIB
 - \rightarrow Au & C coating for SEM

Profilometry

- \rightarrow 3D optical profilometry
- \rightarrow Step height measurement (stylus 2.5 or 25 $\mu m)$

Cross sectioning

- \rightarrow Sample molding in resins followed by grinding and polishing
- \rightarrow Ion beam polisher
- \rightarrow FIB local cross sections integrated in a FEG SEM instrument

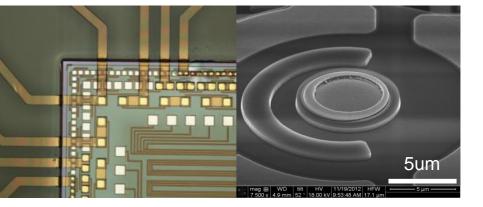
Surface analysis

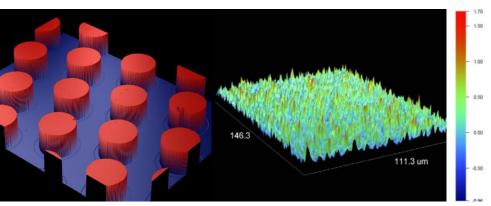
- \rightarrow Contact angle
- \rightarrow Soldarability, Critical Cleanliness Control

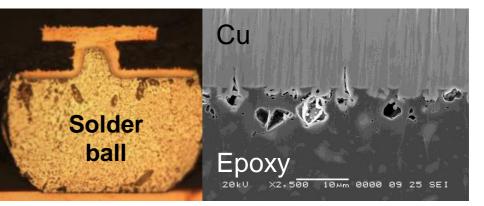
Material analysis

 \rightarrow SEM+EDS

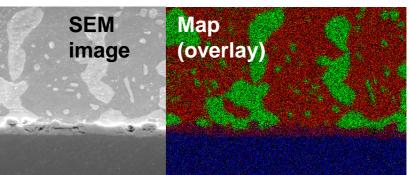












Reliability testing and failure analysis:

Mechanical testing

- \rightarrow Peel test (90° & 180°)
- \rightarrow Component shear and pull testing
- \rightarrow Stress/strain measurements
- \rightarrow Standardized washing tests

Climate chamber testing

- \rightarrow Temperature storage (37 200 °C)
- \rightarrow Temperature-humidity testing (10 95 °C, 10 98 % RH)
- \rightarrow Temperature cycling (-70 °C to 180 °C) with in-situ resistance measurement



(INSTRON)







Universal Testing Machine



Universal Bond Tester

Humidity testing



Thermal cycling

Electrical measurements:

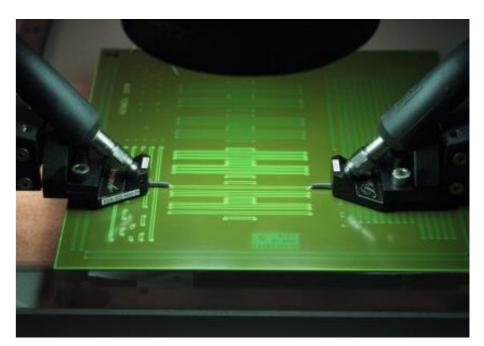
DC measurements

- \rightarrow Contact resistance
- \rightarrow Sheet resistance
- \rightarrow Component characterization (I/V curve, leakage current)
- \rightarrow Surface insulation resistance (linked to climate chamber)

AC measurements

- \rightarrow Electronic circuit analysis
- \rightarrow Impedance and network analysis
- \rightarrow Dielectric withstanding voltage testing up to 6kV





Four-point probe station

OLLABORATION WITH NAMIFAB

Start working with us in three simple steps:

 \rightarrow File a request

Fill out the NaMiFab request form and send it after completion to <u>thomas.vervust@ugent.be</u>

 \rightarrow Feedback from NaMiFab

We will contact you to explain what we can do and we will request more input if needed.

 \rightarrow Execution of the work

Once we both agree on how we will tackle the request, we can start with the actual work.

(Please call or mail if you have questions!)





OLLABORATION WITH NAMIFAB

The NaMiFab request form

 \rightarrow Can be downloaded from the website (see collaboration page)

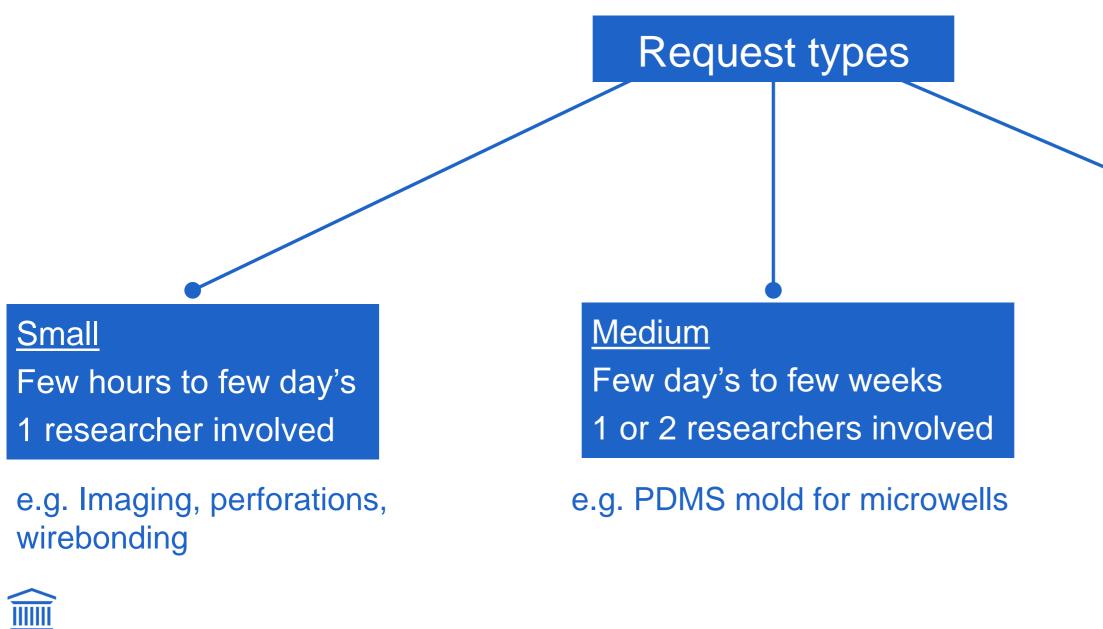
- \rightarrow Should be filled out in a clear and concise way (keep it short)
- \rightarrow Provides us information about:
 - Contact details
 - Background of the research
 - The request itself
 - Expectations on the outcome
 - Future plans (additional requests, paper, project proposal,...)





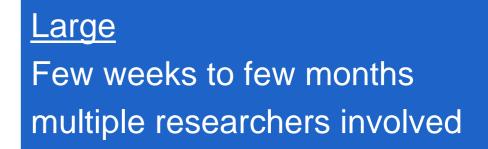
COLLABORATION WITH NAMIFAB

We defined three types of project requests, with different duration and requirements for resources



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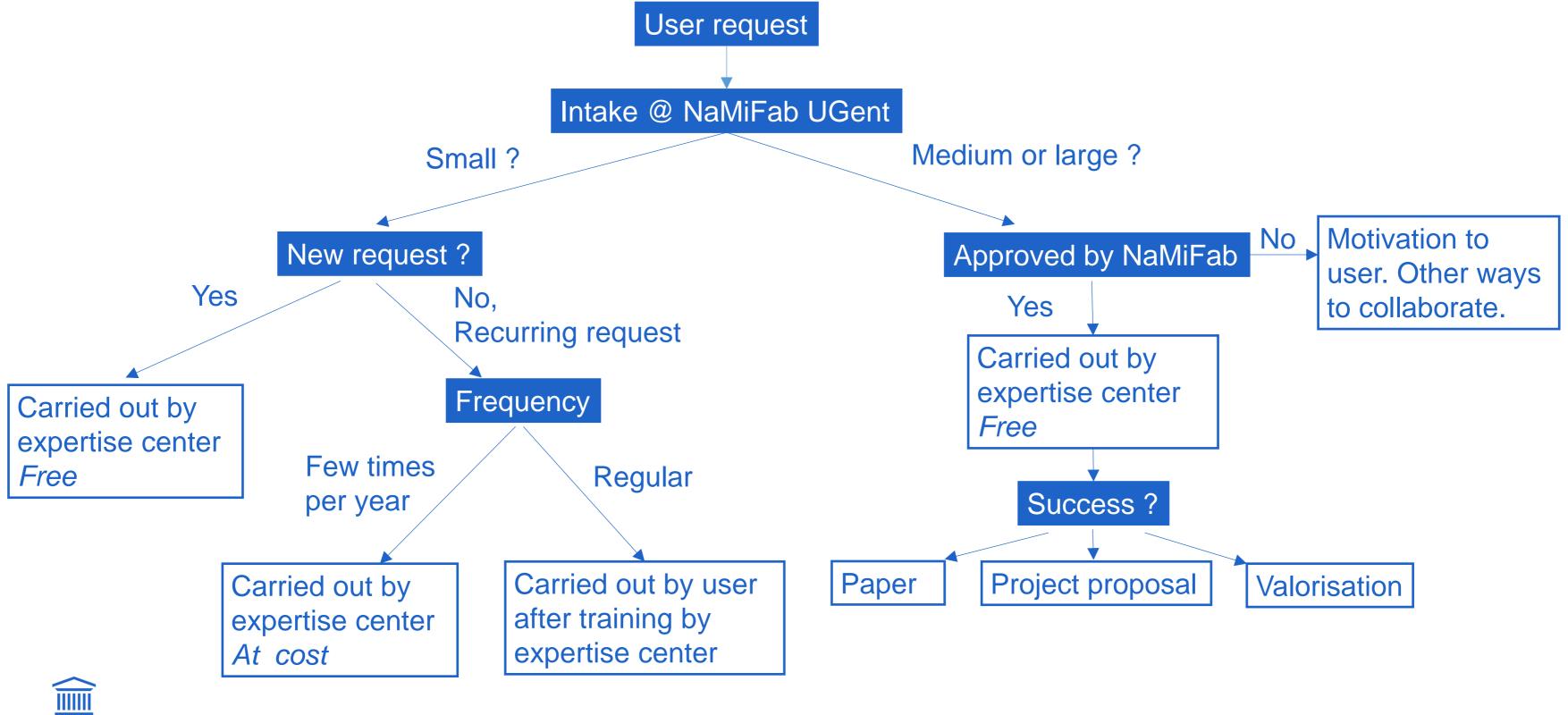




e.g. Party shirt, Light Sheet Microscopy

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COLLABORATION WITH NAMIFAB



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COLLABORATION WITH NAMIFAB

What's the cost for Ugent research groups?

- \rightarrow The aim of NaMiFab is to lower the barrier and hence the costs for first entry as much as possible.
- \rightarrow The target is to accommodate **new requests free of charge** for the user. The user will only be charged in the case of, for example, high consumable costs or special tooling.
- \rightarrow In case of recurring (and hence successful) requests, the user will be requested to carry the costs involved, such as consumables, machine time and operator time (at effective cost).
- \rightarrow Project coordination time will not be charged





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